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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	· ·
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	·
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc716-04i-p

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 1-1: P	IC16C712/71		DESCRIP		
Pin	PIC16C	712/716	Pin	Buffer	
Name	DIP, SOIC	SSOP	Туре	Туре	Description
MCLR/VPP	4	4			
MCLR			I	ST	Master clear (Reset) input. This pin is
VPP			Р		an active low Reset to the device. Programming voltage input
OSC1/CLKIN	16	18	Г		
OSCI/CLKIN OSCI	10	10	1	ST	Oscillator crystal input or external clock
0001				01	source input. ST buffer when config-
					ured in RC mode. CMOS otherwise.
CLKIN			I	CMOS	External clock source input.
OSC2/CLKOUT	15	17			
OSC2			0	_	Oscillator crystal output. Connects to
					crystal or resonator in crystal oscillator mode.
CLKOUT			0		In RC mode, OSC2 pin outputs
GEROOT			Ŭ		CLKOUT which has 1/4 the frequency
					of OSC1, and denotes the instruction
					cycle rate.
					PORTA is a bidirectional I/O port.
RA0/AN0	17	19			
RA0			I/O	TTL	Digital I/O
AN0			I	Analog	Analog input 0
RA1/AN1	18	20	1/0		
RA1 AN1			I/O I	TTL Analog	Digital I/O Analog input 1
		4	I	Analog	Analog input 1
RA2/AN2 RA2	1	1	I/O	TTL	Digital I/O
AN2			1/0	Analog	Analog input 2
RA3/AN3/VREF	2	2	•	,	
RA3	2	£	I/O	TTL	Digital I/O
AN3			I	Analog	Analog input 3
VREF			I	Analog	A/D Reference Voltage input.
RA4/T0CKI	3	3			
RA4			I/O	ST/OD	Digital I/O. Open drain when configured
TOOK				OT	as output.
TOCKI		input C	I	ST OS compatible	Timer0 external clock input

TABLE 1-1: PIC16C712/716 PINOUT DESCRIPTION

 Legend:
 TTL = TTL-compatible input
 CMOS = CMOS compatible input or output

 ST = Schmitt Trigger input with CMOS levels
 OD = Open drain output

 SM = SMBus compatible input. An external resistor is required if this pin is used as an output

 NPU = N-channel pull-up
 PU = Weak internal pull-up

 No-P diode = No P-diode to VDD
 AN = Analog input or output

 I = input
 O = output

 P = Power
 L = LCD Driver

2.2.2.2 OPTION_REG Register

The OPTION_REG register is a readable and writable register, which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

FIGURE 2-5: OPTION_REG REGISTER (ADDRESS 81h)

R/W-1 RBPU	R/W-1	R/W-1 T0CS	R/W-1 T0SE	R/W-1 PSA	R/W-1 PS2	R/W-1 PS1	R/W-1 PS0	R = Readable bit
it7	INTEDG	1003	1032	FGA	F 32	-31	bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR Reset
oit 7:	RBPU : PO 1 = PORTE 0 = PORTE	3 pull-ups	are disal	oled	lividual port	latch valu	es	
oit 6:	INTEDG : I 1 = Interru 0 = Interru	pt on rising	g edge of	f RB0/INT				
oit 5:	TOCS : TMI 1 = Transit 0 = Interna	ion on RA	4/T0CKI	pin	(OUT)			
bit 4:		ent on hig	h-to-low	transition	on RA4/T0 on RA4/T0			
bit 3:	PSA : Pres 1 = Presca 0 = Presca	ler is assi	gned to t	he WDT	module			
bit 2-0:	PS2:PS0 :	Prescaler	Rate Sel	ect bits				
	Bit Value	TMR0 Ra	te WD	Γ Rate				
	000 001 010 011 100 101 110 111	1 : 2 1 : 4 1 : 8 1 : 16 1 : 32 1 : 64 1 : 128 1 : 256	1 : 3 1 :	2				

2.2.2.5 PIR1 Register

This register contains the individual flag bits for the peripheral interrupts.

Note: Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-8: PIR1 REGISTER (ADDRESS 0Ch)

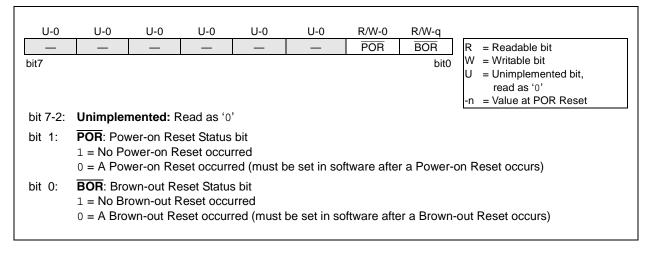
U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0			
 bit7	ADIF — — — CCP1IF TMR2IF TMR1IF bit0 R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'									
bit 7:	Unimpler	nented: R	ead as '0	,				-n = Value at POR Reset		
bit 6:										
bit 5-3:	Unimpler	nented: R	ead as '0	,						
bit 2:	bit 2: CCP1IF: CCP1 Interrupt Flag bit <u>Capture Mode:</u> 1 = A TMR1 register capture occurred (must be cleared in software) 0 = No TMR1 register capture occurred <u>Compare Mode:</u> 1 = A TMR1 register compare match occurred (must be cleared in software) 0 = No TMR1 register compare match occurred <u>PWM Mode:</u> Unused in this mode									
bit 1:	TMR2IF : TMR2 to PR2 Match Interrupt Flag bit 1 = TMR2 to PR2 match occurred (must be cleared in software) 0 = No TMR2 to PR2 match occurred									
bit 0:	TMR1IF: TMR1 Overflow Interrupt Flag bit 1 = TMR1 register overflowed (must be cleared in software) 0 = TMR1 register did not overflow									

2.2.2.6 PCON Register

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external MCLR Reset or WDT Reset. These devices contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition. Note: If the BODEN Configuration bit is set, BOR is '1' on Power-on Reset. If the BODEN Configuration bit is clear, BOR is unknown on Power-on Reset. The BOR Status bit is a "don't care" and is

not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). BOR must then be set by the user and checked on subsequent resets to see if it is clear, indicating a brown-out has occurred.

FIGURE 2-9: PCON REGISTER (ADDRESS 8Eh)



TMR1 Module Mode	Clock Source	Control Bits	TMR1 Module Operation	PORTB<2:1> Operation		
Off	N/A	T1CON =xx 0x00	Off	PORTB<2:1> function as normal I/O		
Timer	Fosc/4	T1CON =xx 0x01	TMR1 module uses the main oscillator as clock source. TMR1ON can turn on or turn off Timer1.	PORTB<2:1> function as normal I/O		
Counter	External circuit	T1CON =xx 0x11 TR1SCCP =x-1	TMR1 module uses the external signal on the RB1/T1OSO/ T1CKI pin as a clock source. TMR1ON can turn on or turn off Timer1. DT1CK can read the signal on the RB1/T1OSO/ T1CKI pin.	PORTB<2> functions as normal I/O. PORTB<1> always reads '0' when configured as input. If PORTB<1> is configured as out- put, reading PORTB<1> will read the data latch. Writing to PORTB<1> will always store the		
	Firmware	T1CON =xx 0x11 TR1SCCP =x-0	DATACCP<0> bit drives RB1/ T1OSO/T1CKI and produces the TMR1 clock source. TMR1ON can turn on or turn off Timer1. The DATACCP<0> bit, DT1CK, can read and write to the RB1/T1OSO/T1CKI pin.	result in the data latch, but not to the RB1/T1OSO/T1CKI pin. If the TMR1CS bit is cleared (TMR1 reverts to the timer mode), then pin PORTB<1> will be driven with the value in the data latch.		
	Timer1 oscillator	T1CON =xx 1x11	RB1/T1OSO/T1CKI and RB2/ T1OSI are configured as a 2 pin crystal oscillator. RB1/T1OSI/ T1CKI is the clock input for TMR1. TMR1ON can turn on or turn off Timer1. DATACCP<1> bit, DT1CK, always reads '0' as input and can not write to the RB1/T1OSO/T1CK1 pin.	PORTB<2:1> always read '0' when configured as inputs. If PORTB<2:1> are configured as outputs, reading PORTB<2:1> will read the data latches. Writ- ing to PORTB<2:1> will always store the result in the data latches, but not to the RB2/ T1OSI and RB1/T1OSO/T1CKI pins. If the TMR1CS and T1OSCEN bits are cleared (TMR1 reverts to the timer mode and TMR1 oscillator is disabled), then pin PORTB<2:1> will be driven with the value in the data latches.		

TABLE 5-1: TMR1 MODULE AND PORTB OPERATION

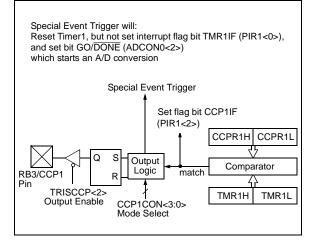
7.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RB3/CCP1 pin is either:

- driven High
- driven Low
- remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time, interrupt flag bit CCP1IF is set.

FIGURE 7-4: COMPARE MODE OPERATION BLOCK DIAGRAM



7.2.1 CCP PIN CONFIGURATION

The user must configure the RB3/CCP1 pin as the CCP output by clearing the TRISCCP<2> bit.

Note:	Clearing the CCP1CON register will force the RB3/CCP1 compare output latch to the default low level. This is neither the CORTE I/O data latch part the DATACCE
	PORTB I/O data latch nor the DATACCP latch.

7.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

7.2.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

7.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated which may be used to initiate an action.

The Special Event Trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The Special Event Trigger output of CCP1 also starts an A/D conversion (if the A/D module is enabled).

Note: The Special Event Trigger from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

TABLE 7-2: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
07h	DATACCP	—	—	—	—	_	DCCP	_	DT1CK	xxxx xxxx	xxxx xuxu
0Bh,8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	_	_	CCP1IF	TMR2IF	TMR1IF	-0000	-0000
0Eh	TMR1L Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								ter	xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding	Registe	r for the Mo	st Significa	nt Byte of th	e 16-bit TN	IR1 Regist	er	xxxx xxxx	uuuu uuuu
10h	T1CON			T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
15h	CCPR1L	Capture/	/Compa	re/PWM Re	gister 1 (LS	6B)				xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register 1 (MSB)							xxxx xxxx	uuuu uuuu	
17h	CCP1CON		—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
87h	TRISCCP	_	_	—	—	—	TCCP	_	TT1CK	xxxx x1x1	xxxx x1x1
8Ch	PIE1	—	ADIE	_	—	_	CCP1IE	TMR2IE	TMR1IE	-0000	-0000

Legend: x = unknown, u = unchanged, -- = unimplemented read as '0'. Shaded cells are not used by Capture and Timer1.

7.3 PWM Mode

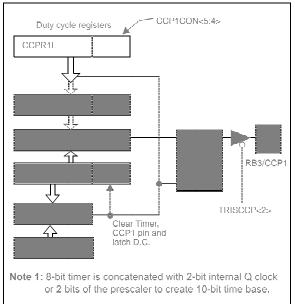
In Pulse Width Modulation (PWM) mode, the CCP1 pin produces up to a 10-bit resolution PWM output. Since the CCP1 pin is multiplexed with the PORTB data latch, the TRISCCP<2> bit must be cleared to make the CCP1 pin an output.

Note:	Clearing the CCP1CON register will force
	the CCP1 PWM output latch to the default
	low level. This is neither the PORTB I/O
	data latch nor the DATACCP latch.

Figure 7-5 shows a simplified block diagram of the CCP module in PWM mode.

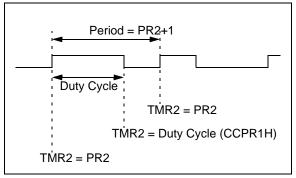
For a step by step procedure on how to set up the CCP module for PWM operation, see **Section 7.3.3** "**Set-Up for PWM Operation**".

FIGURE 7-5: SIMPLIFIED PWM BLOCK DIAGRAM



A PWM output (Figure 7-6) has a time base (period) and a time that the output stays high (duty cycle). The frequency of the PWM is the inverse of the period (1/ period).

FIGURE 7-6: PWM OUTPUT



7.3.1 PWM PERIOD

The PWM period is specified by writing to the PR2 register. The PWM period can be calculated using the following formula:

PWM period = [(PR2) + 1] • 4 • TOSC • (TMR2 prescale value)

PWM frequency is defined as 1 / [PWM period].

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The CCP1 pin is set (exception: if PWM duty cycle = 0%, the CCP1 pin will not be set)
- The PWM duty cycle is latched from CCPR1L into CCPR1H

Note:	The Timer2 postscaler (see Section 6.0				
	"Timer2 Module") is not used in the				
	determination of the PWM frequency. The				
	postscaler could be used to have a servo				
	update rate at a different frequency than				
	the PWM output.				

7.3.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR1L register and to the CCP1CON<5:4> bits. Up to 10-bit resolution is available. The CCPR1L contains the eight MSbs and the CCP1CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPR1L:CCP1CON<5:4>. The following equation is used to calculate the PWM duty cycle in time:

PWM duty cycle = (CCPR1L:CCP1CON<5:4>) • Tosc • (TMR2 prescale value)

CCPR1L and CCP1CON<5:4> can be written to at any time, but the duty cycle value is not latched into CCPR1H until after a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR1H is a read-only register.

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

When the CCPR1H and 2-bit latch match TMR2 concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCP1 pin is cleared.

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)} \quad \text{bits}$$

Note: If the PWM duty cycle value is longer than the PWM period the CCP1 pin will not be cleared.

For an example PWM period and duty cycle calculation, see the $PIC^{\textcircled{B}}$ Mid-Range Reference Manual, (DS33023).

7.4 CCP1 Module and PORTB Operation

When the CCP module is disabled, PORTB<3> operates as a normal I/O pin. When the CCP module is enabled, PORTB<3> operation is affected. Multiplexing details of the CCP1 module are shown on PORTB<3>, refer to Figure 3.6.

Table 7-5 below shows the effects of the CCP module operation on PORTB<3>

CCP1 Module Mode	Control Bits	CCP1 Module Operation	PORTB<3> Operation
Off	CCP1CON =xx 0000	Off	PORTB<3> functions as normal I/O.
Capture	CCP1CON =xx 01xx TRISCCP =1-x	The CCP1 module will capture an event on the RB3/CCP1 pin which is driven by an external circuit. The DCCP bit can read the signal on the RB3/CCP1 pin.	PORTB<3> always reads '0' when configured as input. If PORTB<3> is configured as output, reading PORTB<3> will read the data latch.
	CCP1CON =xx 01xx TRISCCP =0-x	The CCP1 module will capture an event on the RB3/CCP1 pin which is driven by the DCCP bit. The DCCP bit can read the signal on the RB3/CCP1 pin.	Writing to PORTB<3> will always store the result in the data latch, but it does not drive the RB3/CCP1 pin.
Compare	CCP1CON =xx 10xx TRISCCP =0-x	The CCP1 module produces an output on the RB3/CCP1 pin when a compare event occurs. The DCCP bit can read the signal on the RB3/CCP1 pin.	
PWM	CCP1CON =xx 11xx TRISCCP =0-x	The CCP1 module produces the PWM signal on the RB3/CCP1 pin. The DCCP bit can read the signal on the RB3/CCP1 pin.	

TABLE 7-5: CCP1 MODULE AND PORTB OPERATION

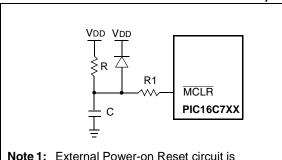
9.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (to a level of 1.5V-2.1V). To take advantage of the POR, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified (parameter D004). For a slow rise time, see Figure 9-5.

When the device starts normal operation (exits the Reset condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

FIGURE 9-5:

EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- te1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
 - **2:** R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.
 - **3:** $R1 = 100\Omega$ to $1 k\Omega$ will limit any current flowing into \overline{MCLR} from external capacitor C in the event of \overline{MCLR}/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

9.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter #33), on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in Reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A Configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

9.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter #32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from Sleep.

9.7 Brown-Out Reset (BOR)

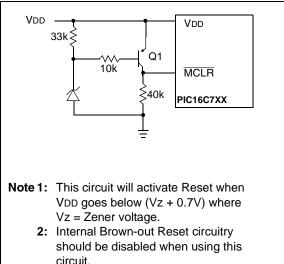
The PIC16C712/716 members have on-chip Brownout Reset circuitry. A Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V, refer to VBOR parameter D005(VBOR) for a time greater than parameter (TBOR) in Table 12-6. The brown-out situation will reset the chip. A Reset is not guaranteed to occur if VDD falls below 4.0V for less than parameter (TBOR).

On any Reset (Power-on, Brown-out, Watchdog, etc.) the chip will remain in Reset until VDD rises above VBOR. The Power-up Timer will now be invoked and will keep the chip in Reset an additional 72 ms.

If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above VBOR, the Power-Up Timer will execute a 72 ms Reset. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-7 shows typical Brown-out situations.

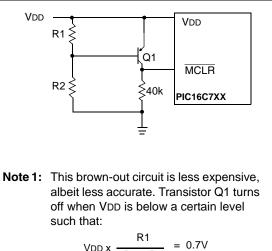
For operations where the desired brown-out voltage is other than 4V, an external brown-out circuit must be used. Figure 9-8, 9-9 and 9-10 show examples of external brown-out protection circuits.







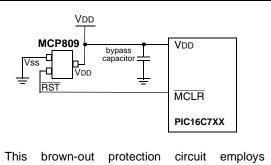
EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



$$\frac{R1}{R1 + R2} = 0$$

- 2: Internal Brown-out Reset should be disabled when using this circuit.
- 3: Resistors should be adjusted for the characteristics of the transistor.

FIGURE 9-10: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



Microchip Technology's MCP809 microcontroller supervisor. The MCP8XX and MCP1XX families of supervisors provide push-pull and open collector outputs with both high and low active Reset pins. There are 7 different trip point selections to accommodate 5V and 3V systems

9.8 **Time-out Sequence**

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 9-11, Figure 9-12, and Figure 9-13 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Then bringing MCLR high will begin execution immediately (Figure 9-13). This is useful for testing purposes or to synchronize more than one PIC16CXXX device operating in parallel.

Table 9-5 shows the Reset conditions for some Special Function Registers, while Table 9-6 shows the Reset conditions for all the registers.

9.16 In-Circuit Serial Programming™

PIC16CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

For complete details on serial programming, please refer to the In-Circuit Serial Programming[™] (ICSP[™]) Guide, (DS30277).

11.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
 - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
 - MPASM[™] Assembler
 - MPLAB C18 and MPLAB C30 C Compilers
 - MPLINK[™] Object Linker/
 - MPLIB™ Object Librarian
 - MPLAB ASM30 Assembler/Linker/Library
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB ICE 2000 In-Circuit Emulator
 - MPLAB ICE 4000 In-Circuit Emulator
- In-Circuit Debugger
 - MPLAB ICD 2
- Device Programmers
- PICSTART[®] Plus Development Programmer
- MPLAB PM3 Device Programmer
- Low-Cost Demonstration and Development Boards and Evaluation Kits

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows[®] operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- · A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Visual device initializer for easy register initialization
- · Mouse over variable inspection
- Drag and drop variables from source to watch windows
- · Extensive on-line help
- Integration of select third party tools, such as HI-TECH Software C Compilers and IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
 - Source files (assembly or C)
 - Mixed assembly and C
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

11.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

11.12 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM[™] and dsPICDEM[™] demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ[®] security ICs, CAN, IrDA[®], PowerSmart[®] battery management, SEEVAL[®] evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) and the latest *"Product Selector Guide"* (DS00148) for the complete list of demonstration, development and evaluation kits.

12.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

Ambient temperature under bias	55°C to +125°C
Ambient temperature under bias Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0V to +13.25V
Voltage on RA4 with respect to Vss	0V to +8.5V
Total power dissipation (Note 1) (PDIP and SOIC)	1.0W
Total power dissipation (Note 1) (SSOP)	
Maximum current out of Vss pin	300 mA
Maximum current into VDD pin	
Input clamp current, Iк (VI < 0 or VI > VDD)	±20 mA
Output clamp current, loк (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTB (combined)	200 mA
Maximum current sourced by PORTA and PORTB (combined)	200 mA
Note the Device disciplination is estimated as follows: $Ddis_{\mathcal{A}}$, $Max_{\mathcal{A}}$, $Max_$	$\lambda(a, y) = \{a, y\} = \sum \{\lambda(a, y) = x\}$

- **Note 1:** Power dissipation is calculated as follows: $Pdis = VDD \times \{IDD \sum IOH\} + \sum \{(VDD-VOH) \times IOH\} + \sum (VOI \times IOL)$ **2:** Voltage spikes below Vss at the MCLR/VPP pin, inducing currents greater than 80 mA, may cause latch-up.
 - Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the MCLR/VPP pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.2 DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)

	Standard Operating Conditions (unless otherwise stated) Operating temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial						
DC CHAI	RACIER	151105	Operating	g tempe	rature	-40°	
Param No.	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions
D001	Vdd	Supply Voltage	2.5 Vbor*	_	5.5 5.5	V V	BOR enabled (Note 7)
D002*	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5	_	V	
D003	VPOR	VDD Start Voltage to ensure internal Power-on Reset signal	—	Vss	—	V	See section on Power-on Reset for details
D004* D004A*	SVDD	VDD Rise Rate to ensure internal Power-on Reset signal	0.05 TBD	_	_	V/ms	PWRT enabled (PWRTE bit clear) PWRT disabled (PWRTE bit set) See section on Power-on Reset for details
D005	VBOR	Brown-out Reset voltage trip point	3.65	—	4.35	V	BODEN bit set
D010 D010A	IDD	Supply Current ^(2,5)	_	2.0 22.5	3.8 48	mA μA	XT, RC osc modes Fosc = 4 MHz, VDD = 3.0V (Note 4) LP osc mode Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D020 D021 D021A	IPD	Power-down Current ^(3,5)		7.5 0.9 0.9	30 5 5	μΑ μΑ μΑ	VDD = $3.0V$, WDT enabled, $-40^{\circ}C$ to $+85^{\circ}C$ VDD = $3.0V$, WDT disabled, $0^{\circ}C$ to $+70^{\circ}C$ VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$
D022* D022A*	ΔIWDT ΔIBOR	Module Differential Current ⁽⁶⁾ Watchdog Timer Brown-out Reset		6.0 TBD	20 200	μΑ μΑ	WDTE bit set, VDD = 4.0V BODEN bit set, VDD = 5.0V
1A	Fosc	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0		200 4 4 20	KHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

 $\underline{OSC1} = external \text{ square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,}$

 \overline{MCLR} = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

12.4.2 TIMING CONDITIONS

The temperature and voltages specified in Table 12-1 apply to all timing specifications, unless otherwise noted. Figure 12-3 specifies the load conditions for the timing specifications.

TABLE 12-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

	Standard Operating Conditions (unless otherwise stated)					
	Operating temperature	0°C	\leq Ta \leq	+70°C	for commercial	
		-40°C	\leq Ta \leq	+85°C	for industrial	
		-40°C	\leq Ta \leq	+125°C	for extended	
AC CHARACTERISTICS	Operating voltage VDD range as described in DC spec Section 12.1 "DC Characteristics:					
	PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial,					
	Industrial, Extended)" and Section 12.2 "DC Characteristics: PIC16LC712/716-04 (Com-					
	mercial, Industrial)". LC parts operate for commercial/industrial temp's only.					

FIGURE 12-3: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

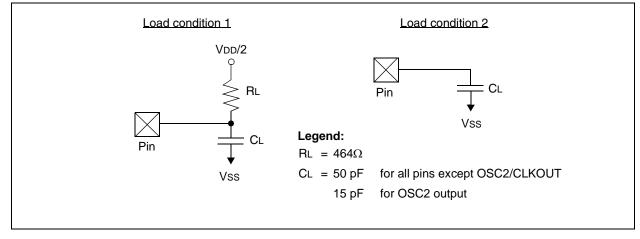


TABLE 12-7:A/D CONVERTER CHARACTERISTICS:
PIC16C712/716-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C712/716-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16LC712/716-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym.	Characteristic		Min.	Тур†	Max.	Units	Conditions
A01	NR	Resolution		_	_	8-bits	bit	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A02	EABS	Total Absolute error		_	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A03	EIL	Integral linearity error		—	-	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A04	Edl	Differential linearity error		_	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A05	Efs	Full scale error		—	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A06	EOFF	Offset error		—	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A10	—	Monotonicity		_	guaranteed (Note 3)	_	_	VSS £ VAIN £ VREF
A20	VREF	Reference voltage		2.5V	_	Vdd + 0.3	V	
A25	VAIN	Analog input voltage		Vss - 0.3		Vref + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	_	10.0	kΩ	
A40	IAD	A/D conversion cur- rent (VDD)	Standard	_	180	_	μΑ	1'
			Extended (LC)	—	90	_	μΑ	
A50 IREF VREF input current (Note 2)		10	_	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 9.1 "Configuration Bits".		
				—	_	10	μΑ	During A/D Conversion cycle

2: * These parameters are characterized but not tested.

3: † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.

The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the Input Voltage, and has no missing codes.

PIC16C712/716

NOTES:

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2/99	This is a new data sheet. How- ever, the devices described in this data sheet are the upgrades to the devices found in the <i>PIC16C6X Data Sheet</i> , DS30234, and the <i>PIC16C7X</i> <i>Data Sheet</i> , DS30390.
В	9/05	Removed Preliminary Status.
С	1/13	Added a note to each package outline drawing.

APPENDIX B: CONVERSION CONSIDERATIONS

There are no previous versions of this device.

APPENDIX C: MIGRATION FROM BASE-LINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
- A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
- 3. Data memory paging is redefined slightly. STATUS register is modified.
- Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW.
 Two instructions TRIS and OPTION are being phased out although they are kept for compati-bility with PIC16C5X.
- 5. OPTION_REG and TRIS registers are made addressable.
- 6. Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- Reset of all registers is revisited. Five different Reset (and wake-up) types are recognized. Registers are reset differently.
- 10. Wake-up from Sleep through interrupt is added.

- 11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change feature.
- 13. T0CKI pin is also a port pin (RA4) now.
- 14. FSR is made a full eight-bit register.
- 15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, Vss, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
- 16. PCON STATUS register is added with a Poweron Reset Status bit (POR).
- 17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- Brown-out protection circuitry has been added. Controlled by Configuration Word bit BODEN. Brown-out Reset ensures the device is placed in a Reset condition if VDD dips below a fixed setpoint.

To convert code written for PIC16C5X to PIC16CXXX, the user should take the following steps:

- 1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change Reset vector to 0000h.

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